
HB56A232 Series

2,097,152-word × 32-bit High Density Dynamic RAM Module

HITACHI

Description

The HB56A232 is a 2M × 32 dynamic RAM module, mounted 16 pieces of 4Mbit DRAM (HM514400CS/CLS) sealed in SOJ package. An outline of the HB56A232 is 72-pin single in-line package. Therefore, the HB56A232 makes high density mounting possible without surface mount technology. The HB56A232 provides common data inputs and outputs. Decoupling capacitors are mounted beneath each SOJ but only on the one side of its module board.

Features

- 72-pin single in-line package
 - Lead pitch : 1.27 mm
- Single 5 V (± 5%) supply
- High speed
 - Access time : 60 ns/70 ns/80 ns (max)
- Low power dissipation
 - Active mode : 4.83 W/4.41 W/3.99 W (max)
 - Standby mode : 168 mW (max)
8.4 mW (max) (L version)
- Fast page mode capability
- 1,024 refresh cycle : 16 ms, 128 ms (L-version)
- 2 variations of refresh
 - $\overline{\text{RAS}}$ -only refresh
 - $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh
- TTL compatible

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Ordering Information

Type No.	Access time	Package	Contact pad
HB56A232BW-6C	60 ns	72-pin SIP socket type	gold
HB56A232BW-7C	70 ns		
HB56A232BW-8C	80 ns		
HB56A232BW-6CL	60 ns	72-pin SIP socket type	solder
HB56A232BW-7CL	70 ns		
HB56A232BW-8CL	80 ns		
HB56A232SBW-6C	60 ns	72-pin SIP socket type	solder
HB56A232SBW-7C	70 ns		
HB56A232SBW-8C	80 ns		
HB56A232SBW-6CL	60 ns	72-pin SIP socket type	solder
HB56A232SBW-7CL	70 ns		
HB56A232SBW-8CL	80 ns		

Note: The specification of this device is subject to change without notice. Please contact your nearest Hitachi's Sales Dept. regarding specification.